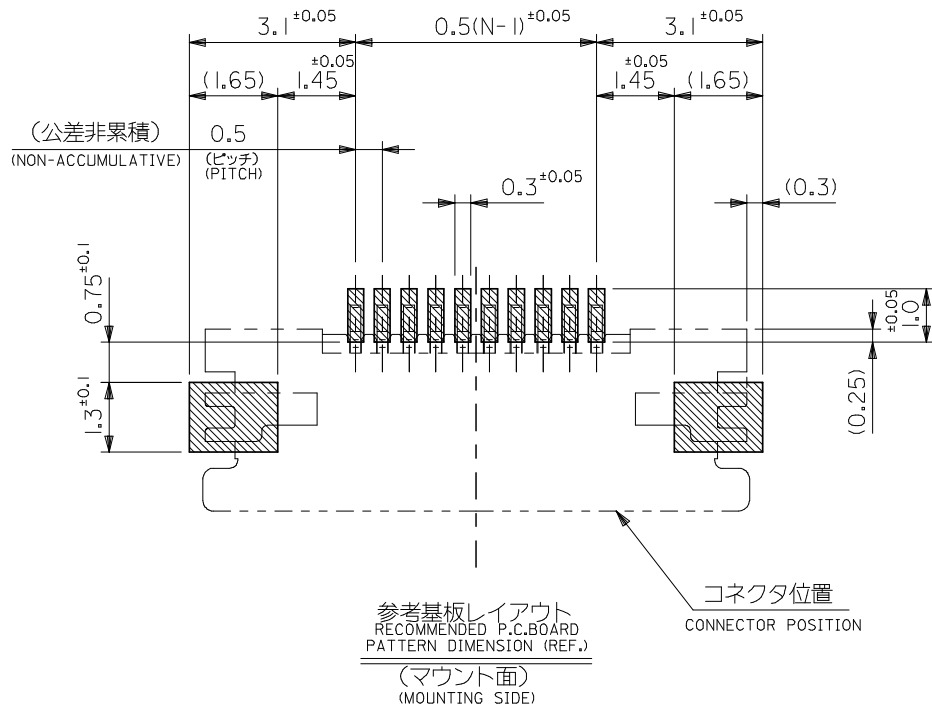


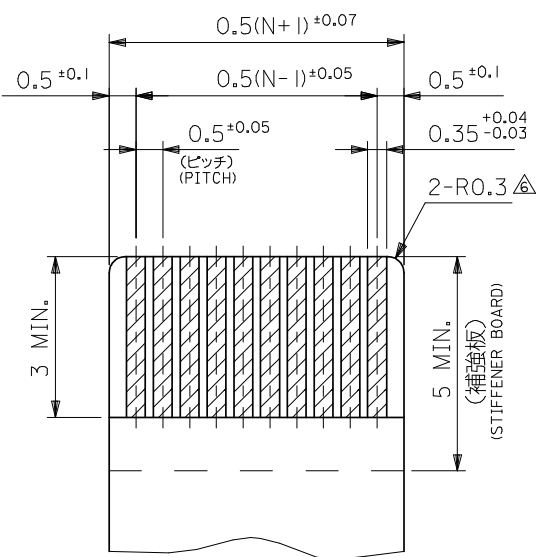
SECT. J-J  
SCALE 20:1

0.28±0.03	13.65	17.0	12.5	18.2	54548-2671	54548-2629	26
	12.65	16.0	11.5	17.2	54548-2471	54548-2429	24
	12.15	15.5	11.0	16.7	54548-2371	54548-2329	23
	11.65	15.0	10.5	16.2	54548-2271	54548-2229	22
	11.15	14.5	10.0	15.7	54548-2171	54548-2129	21
	10.65	14.0	9.5	15.2	54548-2071	54548-2029	20
	10.15	13.5	9.0	14.7	54548-1971	54548-1929	19
	9.65	13.0	8.5	14.2	54548-1871	54548-1829	18
	9.15	12.5	8.0	13.7	54548-1771	54548-1729	17
	8.65	12.0	7.5	13.2	54548-1671	54548-1629	16
	8.15	11.5	7.0	12.7	54548-1571	54548-1529	15
	7.65	11.0	6.5	12.2	54548-1471	54548-1429	14
	7.15	10.5	6.0	11.7	54548-1371	54548-1329	13
6.65	10.0	5.5	11.2	54548-1271	54548-1229	12	
6.15	9.5	5.0	10.7	54548-1171	54548-1129	11	
5.65	9.0	4.5	10.2	54548-1071	54548-1029	10	
5.15	8.5	4.0	9.7	54548-0971	54548-0929	9	
4.65	8.0	3.5	9.2	54548-0871	54548-0829	8	
4.15	7.5	3.0	8.7	54548-0771	54548-0729	7	
3.65	7.0	2.5	8.2	54548-0671	54548-0629	6	
3.15	6.5	2.0	7.7	54548-0571	54548-0529	5	
2.65	6.0	1.5	7.2	54548-0471	54548-0429	4	
FPC THICKNESS	D	C	B	A	EMBOSSED TAPE ORDER No. オータ-番別	製品番号 MATERIAL No.	極数 Ck+

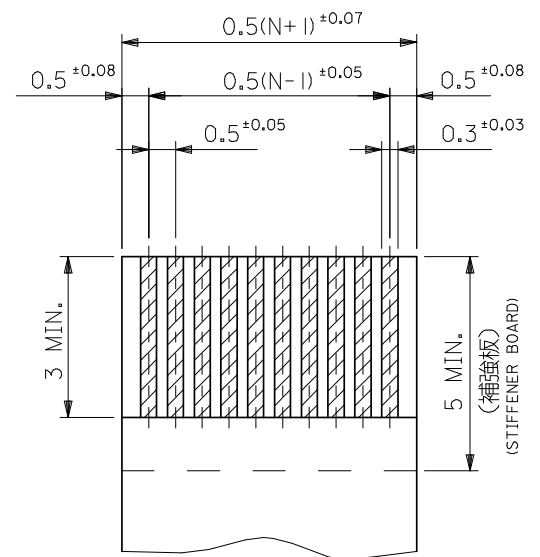
REVISED EC NO: J2008-4048 DRWN:MNABEI 2008/06/13 CH'KD:THARUYAMA 2008/06/16 APPR:NUKITA 2008/06/16	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION	
			MM ONLY	10:1	METRIC		
	10 UNDER	±0.2	DRAWN BY	DATE	TITLE		
	10 OVER 30 UNDER	±0.25	HSHIMABUKURO	'04/02/10	0.5 FPC CONN ZIF HSG ASSY FOR SMT RA BTM CONT -LEAD FREE-		
	30 OVER	±0.3	CHECKED BY	DATE			
ANGULAR ±3°		APPROVED BY	DATE	MOLEX INCORPORATED			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MSASAO	'04/02/10	MATERIAL NO.	DOCUMENT NO.	SHEET NO.	
		SEE TABLE		SD-54548-039	1 OF 2		
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							



参考基板レイアウト  
RECOMMENDED P.C.B. BOARD  
PATTERN DIMENSION (REF.)  
(マウント面)  
(MOUNTING SIDE)



適合FPC推奨寸法  
APPLICABLE FPC  
RECOMMENDED DIMENSION  
(仕上がり厚さ:表参照)  
(THICKNESS:SEE CHART)



適合FFC推奨寸法  
APPLICABLE FFC  
RECOMMENDED DIMENSION  
(仕上がり厚さ:表参照)  
(THICKNESS:SEE CHART)

注記 NOTES

- I. 使用材料 MATERIAL
- ハウジング : LCP, UL94V-0
  - アクチュエータ : PPS, UL94V-0
  - ターミナル :リン青銅 (t=0.2)
  - メッキ : 接点部:金メッキ
  - テール部:錫メッキ
  - 金具 :リン青銅、錫メッキ (t=0.2)

- △パターンはくり止め用金具
- △RO.3はFPC導体部にかからないこと
- 7.本製品は54548-\*\*-21の鉛フリー(部分金メッキ)品である。
- 8. N: 極数 N: CIRCUIT.

2. エンボステープ梱包時は、アクチュエータがロックした状態とする。
- △ソルダーテール半田付け面のズレ量、及び金具半田付け面のズレ量は、基準面 Z に対し上方向 OMAX.、下方向 0.15MAX.とし
  - △偶数極に適用。

FPC/FFC について:

打ち抜き方向は導体側から補強板側を推奨します。  
導体部については軟銅箔35μmまたは50μmを推奨します。  
ABOUT FPC/FFC  
RECOMMENDED PUNCHER DIRECTION : FROM CONDUCTOR SIDE TO STIFFENER FILM SIDE.  
RECOMMENDED CONDUCTOR SPEC :  
THICKNESS OF SOFT COPPER FOIL : 35 MICROMETER OR 50 MICROMETER.

FPC について:

補強フィルム材質はポリイミドを推奨します。ベースフィルムは25μmを推奨します。  
接着剤は熱硬化接着剤を推奨します。  
尚、接着剤の接点部への付着は導通不良の原因になりますので、染み出しが無い様、お願い致します。  
ABOUT FPC  
RECOMMENDED MATERIAL/THICKNESS.  
STIFFENER FILM : POLYIMIDE  
BASE FILM THICKNESS : 25μm  
BONDING AGENT : THERMOSETTING BONDING AGENT  
PLEASE PUT APPROPRIATE AMOUNT OF ADHESIVE ON THE CONTACT AREA BECAUSE THE EXTRA ADHESIVE MAY CAUSE THE DEFECT IN ELECTRICAL CONTINUITY.

REVISED EC NO: J2008-4048 DRWN:WABEI CHKD:THARYAMA APPR:NUKITA	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE ---	DESIGN UNITS METRIC	MODEL No. 54548-**-29	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY HSHIMABUKURO	DATE '04/02/10	TITLE 0.5 FPC CONN ZIF HSG ASSY FOR SMT RA BTM CONT -LEAD FREE-		
	10 OVER 30 UNDER	±0.25	CHECKED BY KTOJO	DATE '04/02/10	MOLEX INCORPORATED		
	30 OVER	±0.3	APPROVED BY MSASAO	DATE '04/02/10	DOCUMENT NO. SD-54548-039		
	ANGULAR ±3°		MATERIAL NO. SEE SHEET 1	DOCUMENT NO. SD-54548-039		SHEET NO. 2 OF 2	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					